

N-Channel 500V (D-S) Super Junction Power MOSFET

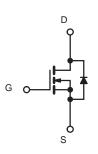
PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	500)
R _{DS(on)} at 25 °C (Ω)	V _{GS} = 10 V	0.085

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qa)
- Avalanche energy rated (UIS)

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting



N-Channel MOSFET





Top View

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	500	V	
Gate-Source Voltage			V_{GS}	± 30	7 °	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	I _D	33		
	VGS at 10 V	T _C = 100 °C		20	A	
Pulsed Drain Current ^a			I _{DM}	100		
Linear Derating Factor				1.67	W/°C	
Single Pulse Avalanche Energy b			E _{AS}	980	mJ	
Maximum Power Dissipation			P_{D}	310	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 125 °C		-I) / /-I±	50	1//	
Reverse Diode dV/dt d		dV/dt	15	- V/ns		
Soldering Recommendations (Peak Temperature) ^c	for '	10 s		260	°C	

- a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD}=100$ V, starting $T_J=25$ °C, L = 30mH, $R_g=25$ Ω , $I_{AS}=16A$.

- c. 1.6 mm from case. d. $I_{SD} \le I_D$, dl/dt = 100 A/ μ s, starting T_J = 25 °C.



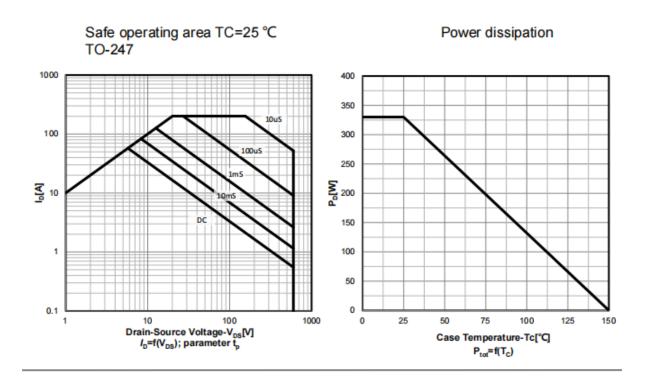
THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	0.38	C/VV

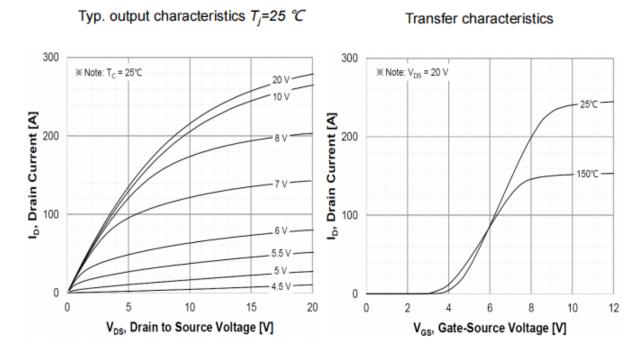
PARAMETER	SYMBOL	ise noted) TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•					
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 1 mA	500	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.5	-	4.5	V
			V _{GS} = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 1	μA
		V _{DS} =	= 500V, V _{GS} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I_{DSS}		/, V _{GS} = 0 V, T _J = 125 °C	-	-	100	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 11A	-	0.085	-	Ω
Forward Transconductance	9fs	V _{DS} = 30 V, I _D = 11 A		-	5.6	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	3600	-	pF
Output Capacitance	Coss			-	3 3 0	-	
Reverse Transfer Capacitance	C _{rss}			-	4	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	- V _{DS} = 0 V to 520 V, V _{GS} = 0 V		-	63	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	213	-	
Total Gate Charge	Qg			-	1 4 8	-	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 \text{ V}$	$I_D = 20 \text{ A}, V_{DS} = 520 \text{ V}$	-	3 9	-	nC
Gate-Drain Charge	Q_{gd}			ı	4 7	-	
Turn-On Delay Time	$t_{d(on)}$			ı	18	25	
Rise Time	t _r	$V_{DD} = 520 \text{ V}, I_D = 20A,$		ı	24	55	ns
Turn-Off Delay Time	t _{d(off)}			ı	8 0	-	113
Fall Time	t _f	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$			1 2	-	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	0.8	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym	MOSFET symbol showing the		1	3 3	_
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	1 0 0	A
Diode Forward Voltage	V _{SD}	T _J = 25 °	C, I _S = 8 A, V _{GS} = 0 V	-	-	1.5	V
Reverse Recovery Time	t _{rr}	-		-	520	-	ns
Reverse Recovery Charge	Q _{rr}	T _J = 25 °C, $I_F = I_S = 8 \text{ A}$, $dI/dt = 100 \text{ A/}\mu\text{s}$, $V_R = 400 \text{ V}$		-	5.8	-	μC
Reverse Recovery Current	I _{RBM}				4 5	_	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .





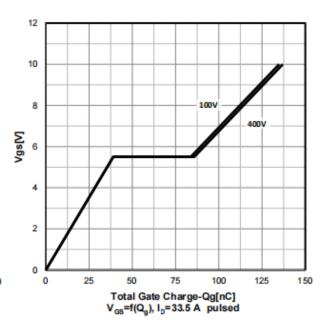




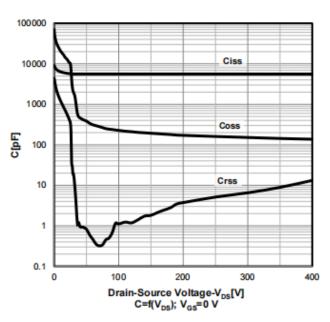
Typ. drain-source on-state resistance

80
70
60
60
40
30
20
0 15 30 45 60 75 90
Drain-Source Current-I_D[A]
R_{DS}(on)=f(I_D); parameter: V_{GS}

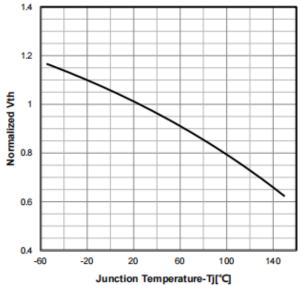
Typ. gate charge characteristics



Typ. capacitances

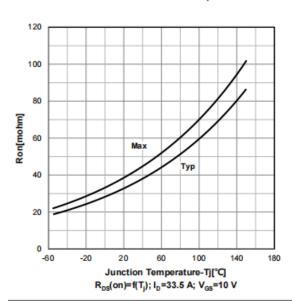


Normalized $V_{\text{GS(th)}}$ characteristics

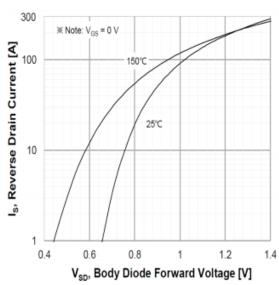




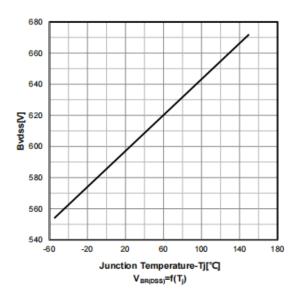
On-resistance vs temperature



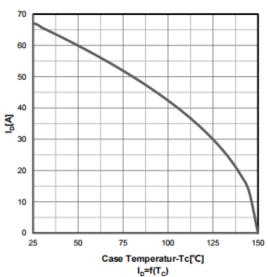
Forward characteristics of reverse diode



Drain-source breakdown voltage



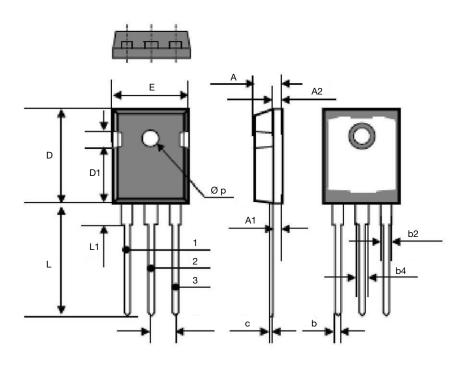
Drain current vs temperature



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TO-247



DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.70	5.31	0.185	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b2	1.65	2.41	0.065	0.095	
b4	2.59	3.43	0.102	0.135	
С	0.61 BSC		0.024 BSC		
D	20.80	21.46	0.819	0.845	
D1	3.68	5.49	0.145	0.216	
(e)	5.46 BSC		0.215 BSC		
E	15.49	16.26	0.610	0.640	
L	19.81	20.32	0.780	0.800	
L1	4.06	4.50	0.160	0.177	
Øр	3.51	3.66	0.138	0.144	



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